



Protection IC for ringing SLICs

Features

- Protection IC recommended for ringing SLICs
- Wide firing voltage range: -120 V to +120 V
- Low gate triggering current: I_G = 5 mA max
- Peak pulse current: $I_{PP} = 30 \text{ A} (10/1000 \text{ µs})$
- Holding current: I_H = 150 mA min
- UL497B approved (file E136224)

Applications

- Dual battery supply voltage SLICs
 - negative battery supply configuration
 - negative and positive battery supply configuration
- Central office (CO)
- Private branch exchange (PBX)
- Digital loop carrier (DLC)
- Asymmetrical digital subscriber line (ADSL G.Lite)
- Fiber in the Loop (FITL)
- Wireless local loop (WLL)
- Hybrid fiber coax (HFC)
- ISDN terminal adapter
- Cable modem

Description

The LCP02-150B1 has been developed to protect SLICs operating on both negative and positive battery supplies, as well as high voltage SLICs. It provides crowbar mode protection for both TIP and RING lines. The surge suppression is assumed for each wire by two thyristor structures, one dedicated to positive surges the second one for negative surges. Both positive and negative threshold levels are programmable by two gates (Gn and Gp). The use of transistors decreases the battery currents during surge suppression.



Figure 1. Functional diagram

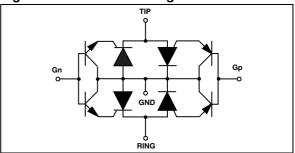
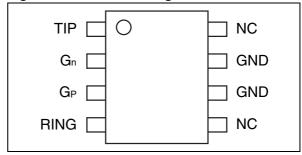


Figure 2. Pin-out configuration



LCP02-150B1 is used to help equipment to meet various standards such as UL1950, IEC 60950 / CSAC22.2, UL1459 and TIA-968-A (formerly FCC part68). Trisils have UL94 V0 resin approved (Trisils are UL497B approved - file: E136224).

Characteristics LCP02-150B1

1 Characteristics

Table 1. Compliant with the following standards

STANDARD	Peak Surge Voltage (V)	Voltage Waveform	Required peak current (A)		Minimum serial resistor to meet standard (Ω)
GR-1089 Core First level	2500 1000	2/10 μs 10/1000 μs	500 100	2/10 μs 10/1000 μs	20.0 24
GR-1089 Core Second level	5000	2/10 µs	500	2/10 µs	43
GR-1089 Core Intra-building	1500	2/10 µs	100	2/10 µs	0
ITU-T-K20/K21	6000 4000 1500	10/700 μs	150 100 37.5	5/310 μs	91 51 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0
VDE0433	4000 2000	10/700 μs	100 50	5/310 µs	51 42
VDE0878	4000 2000	1.2/50 µs	100 50	1/20 µs	22 0
IEC61000-4-5	4000 4000	10/700 μs 1.2/50 μs	100 100	5/310 μs 8/20 μs	5 0
TIA-968-A (formerly FCC part 68) type A	1500 800	10/160 μs 10/560 μs	200 100	10/160 μs 10/560 μs	20 15
TIA-968-A (formerly FCC part 68) type B	1000	9/720 µs	25	5/320 µs	0

Table 2. Absolute maximum ratings ($T_{amb} = 25$ °C)

Symbol	Parameter	Value	Unit	
Ірр	Peak pulse current 10/1000 μs 5/310 μs 2/10μs		30 45 100	А
I _{TSM}	Non repetitive surge peak on-state current (F = 50 Hz) $I_{TSM} \text{ value specified for each line} \\ I_{TSM} \text{ value can be applied on both lines at the same time} \\ \text{(GND capability is twice the line } I_{TSM}) \\ tp = 0.2 \text{ s} \\ tp = 1s \\ tp = 15 \text{ min} \\ tp $		9 6 1.9	A
V _{GN} max V _{GP} max				
T _{op}	Operating temperature range	-40 to +125	°C	
T _{stg}	Storage temperature range	-55 to +150	°C	
TL	Lead solder temperature (10 s duration)	260	°C	

LCP02-150B1 Characteristics

Figure 3. Pulse waveform

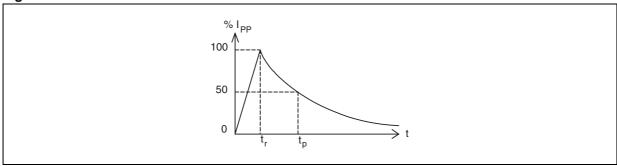


Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-a)}	Junction to ambient	150	°C/W

Table 4. Parameters related to the negative suppressor

Symbol	Parameter	Test conditions	Min	Max	Unit
I _{Gn}	Negative gate trigger current	V _{Gn/GND} = -60 V Measured at 50 Hz		5	mA
I _{H-}	Holding current (see Figure 4)	Go-No Go test, V _{Gn} = -60 V	150		mA
V _{DGL} .	Dynamic switching voltage Gn / Line ⁽¹⁾	$\begin{split} &V_{Gn/GND} = \text{-}60V \\ &10/1000 \; \mu \text{s} 1 \; \text{kV} \qquad R_P = 25 \; \Omega \qquad I_{PP} = 30 \; \text{A} \\ &10/700 \; \mu \text{s} \qquad 2 \; \text{kV} \qquad R_P = 25 \; \Omega \qquad I_{PP} = 30 \; \text{A} \\ &1.2/50 \; \mu \text{s} \qquad 2 \; \text{kV} \qquad R_P = 25 \; \Omega \qquad I_{PP} = 30 \; \text{A} \end{split}$		18 8 15	V

^{1.} The V_{DGL} value is the difference between the peak line voltage during the surge and the programmed gate voltage.

Table 5. Parameters related to the positive suppressor

Symbol	Parameter	Test conditions	Min	Max	Unit
I _{Gp}	Positive gate trigger current	V _{Gn/GND} = 60 V Measured at 50 Hz		5	mA
		V _{Gn/GND} = 60 V			
V _{DGL+} Dynamic switching voltage Gn / Line ⁽¹⁾	10/1000 μs 1 kV $R_P = 25 \Omega$ $I_{PP} = 30 A$		18	V	
	$10/700 \mu\text{s}$ 2 kV $R_P = 25 \Omega$ $I_{PP} = 30 \text{A}$		8		
		1.2/50 μ s 2 kV R _P = 25 Ω I _{PP} = 30 A		35	

^{1.} The V_{DGL} value is the difference between the peak line voltage during the surge and the programmed gate voltage.

Table 6. Parameters related to line/gnd

Symbol	Parameter	Test conditions	Min	Max	Unit
I _R	Reverse leakage current	$\begin{split} T_{j} &= 25 \text{ °C} & V_{LINE} = +120 \text{ V} & V_{GP/LINE} = +1 \text{ V} \\ T_{j} &= 25 \text{ °C} & V_{LINE} = -120 \text{ V} & V_{GN/LINE} = -1 \text{ V} \end{split}$		5 5	μА
C _{off}	Capacitance LINE/GND	$V_R = -3 \text{ V}, \text{ F} = 1 \text{ MHz}, V_{Gp} = 60 \text{ V}, V_{Gn} = -60 \text{ V}$	60		pF

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Table 7. Recommended gate capacitance

Symbol	Component		Тур	Max	Unit
C _G	Gate decoupling capacitance		220		nF

Figure 4. Relative variation of holding current versus junction temperature

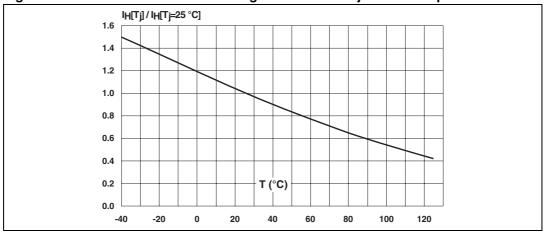


Figure 5. Maximum non repetitive surge peak on state current versus overload duration

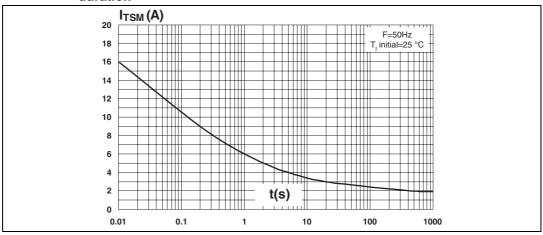
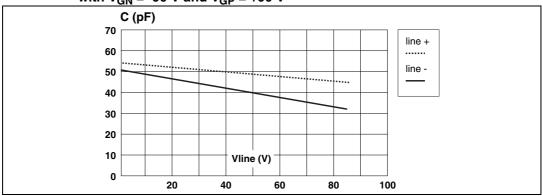


Figure 6. Capacitance versus reverse applied voltage (typical values) with V_{GN} = -90 V and V_{GP} = +90 V



LCP02-150B1 Technical information

2 Technical information

Figure 7. LCP02 concept behavior.

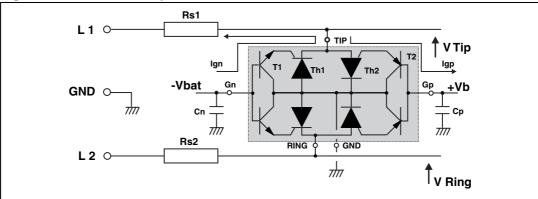


Figure 7 shows the classical protection circuit using the LCP02 crowbar concept. This topology has been developed to protect the new two-battery voltage SLICs. It allows both positive and negative firing thresholds to be programmed. The LCP02-150B1 has two gates (Gn and Gp). Gn is biased to negative battery voltage -Vbat, while Gp is biased to the positive battery voltage +Vb.

When a negative surge occurs on one wire (L1 for example), a current Ign flows through the base of the transistor T1 and then injects a current in the gate of the thyristor Th1 which fires. All the surge current flows through the ground. After the surge, when the current flowing through Th1 becomes less negative than the negative holding current Ih-, Th1 switches off. This holding current IH- is temperature dependant as per *Figure 4*

When a positive surge occurs on one wire (L1 for example), a current Igp flows through the base of the transistor T2 and then injects a current in the gate of the thyristor Th2 which fires. All the surge current flows through the ground. After the surge, when the current flowing through Th2 becomes less positive than the positive holding current Ih+, Th2 switches off. This holding current IH+, typically 20mA at 25°C, is temperature dependant and the same *Figure 4* also applies.

The capacitors Cn and Cp are used to speed up the crowbar structure firing during the fast rise or fall edges. This allows to minimize the dynamical breakover voltage at the SLIC Tip and Ring inputs during fast surges. Please note that these capacitors are generally available around the SLIC. To be efficient they have to be as close as possible to the LCP02-150B1 gate pins (Gn and Gp) and to the reference ground track (or plan). The optimized value for Cn and Cp is 220nF.

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Technical information LCP02-150B1

The series resistors Rs1 and Rs2 designed in *Figure 7* represent the fuse resistors or the PTCs which are needed to withstand the power contact or the power induction tests imposed by the country standards. Taking this factor into account, the actual lightning surge current flowing through the LCP02-150B1 is equal to:

With

V surge = peak surge voltage imposed by the standard.

Rg = series resistor of the surge generator

Rs = series resistor of the line card (e.g. PTC)

For a line card with 50 Ω of series resistors which has to be qualified under Bellcore 1000 V 10/1000 μ s surge, the present current through the LCP02-150B1 is equal to :

I surge =
$$1000 / (10 + 50) = 17 A$$

The LCP02-150B1 topology is particularly optimized for the new telecom applications such as fiber in the loop, WLL systems, decentralized central office for example.

Figure 8. Protection of SLIC with positive and negative battery voltages.

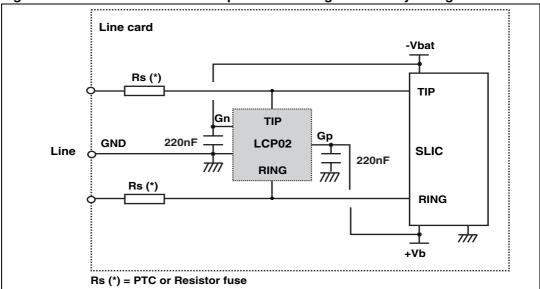


Figure 8 shows the classical protection topology for SLIC using both positive and negative battery voltages. With such a protection the SLIC is protected against surge over +Vb and lower than -Vbat. In this case, +Vb can be programmed up to +120 V while -Vbat can be programmed down to -120 V.

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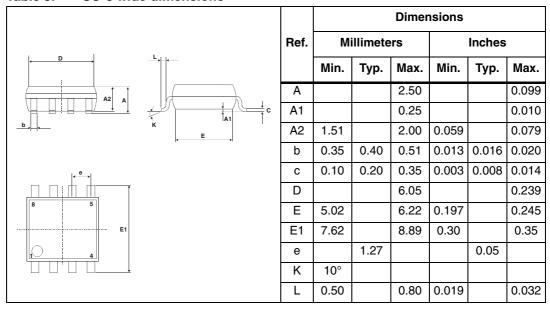
LCP02-150B1 **Package information**

3 **Package information**

Epoxy meets UL94, V0

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at www.st.com.

Table 8. **SO-8 wide dimensions**



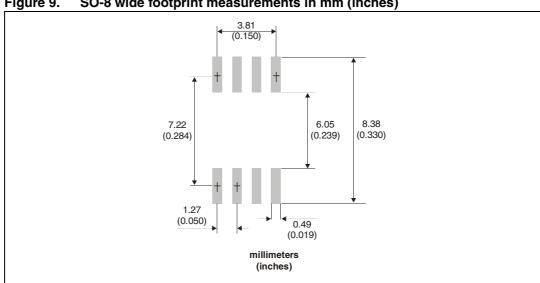


Figure 9. SO-8 wide footprint measurements in mm (inches)

Ordering information LCP02-150B1

4 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
LCP02-150B1RL	LCP02	SO-8-Wide	0.13g	1500	Tape and reel

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
Sep-2000	4A	Previous release.
17-Oct-2008	5	Reformatted to current standards. V _{line} updated to 120 V in <i>Table 6</i> .

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